

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 – 3 (Cancelled)

4. (Currently Amended) A print assembly for pagewidth inkjet printing, the print assembly comprising

an elongate carrier that is mountable on a support structure of a printer in an operative position with respect to a platen of the printer;

a number of printhead chips positioned on the carrier, the printhead chips each having a plurality of ink ejection nozzle arrangements on a wafer substrate, each nozzle arrangement having an actuator for ejecting ink from an associated nozzle when a resistive element of said actuator is heated by an electrical current supplied by drive circuitry on the wafer substrate; and

at least one a plurality of controllers, each controller mounted on a respective printed circuit board that is positioned on the carrier, the each controller being connected to a plurality of the printhead chips via a individual flexible printed circuit board boards of each printhead chip and to the other controllers, and each controller being configured to control operation of at least 10,000 nozzle arrangements of the connected printhead chips.

5. - 6. (Cancelled)

7. (Previously Presented) A print assembly as claimed in claim 4, in which the printhead chips together incorporate at least one hundred thousand nozzle arrangements.

8. (Previously Presented) A print assembly as claimed in claim 4, in which the printhead chips together incorporate at least two hundred thousand nozzle arrangements.

9. (Original) A print assembly as claimed in claim 8, which includes between forty and one hundred printhead chips positioned on the carrier.

10. (Original) A print assembly as claimed in claim 4, in which each printhead chip is the product of an integrated circuit fabrication process.

11. (Previously Presented) A print assembly as claimed in claim 10, in which and the drive circuitry is comprised in a CMOS drive circuitry layer positioned on the wafer substrate with the nozzle arrangements positioned on the wafer substrate and the CMOS drive circuitry layer.

12. (Previously Presented) A print assembly as claimed in claim 11, in which each nozzle arrangement is electrically connected to the CMOS drive circuitry layer.

13. (Original) A print assembly as claimed in claim 12, which includes a plurality of printhead modules, each printhead module incorporating a printhead chip, the printhead modules being mounted on the carrier.

14-20. (Cancelled)